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**JUL 27 2007**REMARKS

The application has been reviewed in light of the final Office Action dated May 3, 2007. Claims 1-6, 8, 9, 11-13 and 15-32 were pending, with claims 15-32 having been withdrawn by the Patent Office from examination. Claims 7, 10, and 14 were previously canceled, without prejudice or disclaimer. By this Amendment, withdrawn claims 15-32 have been canceled, without prejudice or disclaimer, and claim 1 has been amended to clarify the claimed subject matter. Accordingly, claims 1-6, 8, 9 and 11-13 are presented for reconsideration, with claim 1 being in independent form.

Claims 1-6, 8, 9 and 11-13 were rejected under 35 U.S.C. § 102(b) as purportedly anticipated by U.S. Patent No. 6,338,545 (Sekiya '545).

Applicant has carefully considered the Examiner's comments and the cited art, and respectfully submits that independent claim 1 is patentable over the cited art, for at least the following reasons.

This application relates to improvements to techniques for forming a wiring pattern on a device substrate by utilizing a jet unit that ejects droplets of a solution containing conductive fine particles onto the substrate. Applicant devised an improved solution jet type fabrication apparatus comprising a jet head for ejecting droplets of a solution containing conductive fine particles onto a substrate, so as to form a pattern, by vaporizing a volatile ingredient of the solution, and allowing a solid component to remain on the substrate. The thickness of the pattern formed by such an improved apparatus, after vaporizing the volatile ingredient of the solution, is from the diameter of the fine particle to 100 $\mu$ m, and the distance between the fine particles in the pattern is within ten times of the diameter of the particle (see also specification at page 48, line

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13 through page 49, line 2). Independent claim 1 of the present application addresses these features, as well as additional features. Thus, patterns can be formed on device substrates with high precision, and high quality by utilizing applicant's improved apparatus.

Sekiya '545 is directed to an apparatus devised by applicant for performing liquid jet recording onto a medium (such as paper) by jetting ink droplets onto the recording paper.

Sekiya '545 does not teach or suggest a solution jet type fabrication apparatus comprising a jet head for ejecting a droplet of a solution containing conductive fine particles onto a substrate, so as to form a pattern, by vaporizing a volatile ingredient of the solution, and allowing a solid component to remain on the substrate, wherein the thickness of the pattern formed by the apparatus, after vaporizing the volatile ingredient of the solution, is from the diameter of the fine particle to 100 $\mu$ m, and the distance between the fine particles in the pattern is within ten times of the diameter of the particle, as provided by the subject matter of claim 1 of the present application.

Further, applicant submits that it would not have been obvious to modify the apparatus proposed in Sekiya '545 to obtain a solution jet type fabrication apparatus comprising a jet head for ejecting a droplet of a solution containing conductive fine particles onto a substrate, so as to form a pattern, by vaporizing a volatile ingredient of the solution, and allowing a solid component to remain on the substrate, wherein the thickness of the pattern formed by the apparatus, after vaporizing the volatile ingredient of the solution, is from the diameter of the fine particle to 100 $\mu$ m, and the distance between the fine particles in the pattern is within ten times of the diameter of the particle.

Accordingly, for at least the above-stated reasons, Applicant respectfully submits that

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independent claim 1 and the claims depending therefrom, are patentable over the cited art.

In view of the remarks hereinabove, Applicant submits that the application is now in condition for allowance, and earnestly solicits the allowance of the application.

If a petition for an extension of time is required to make this response timely, this paper should be considered to be such a petition. The Patent Office is hereby authorized to charge any fees that are required in connection with this amendment and to credit any overpayment to our Deposit Account No. 03-3125.

If a telephone interview could advance the prosecution of this application, the Examiner is respectfully requested to call the undersigned attorney.

Respectfully submitted,

  
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